

## Standard SCRs, 16A

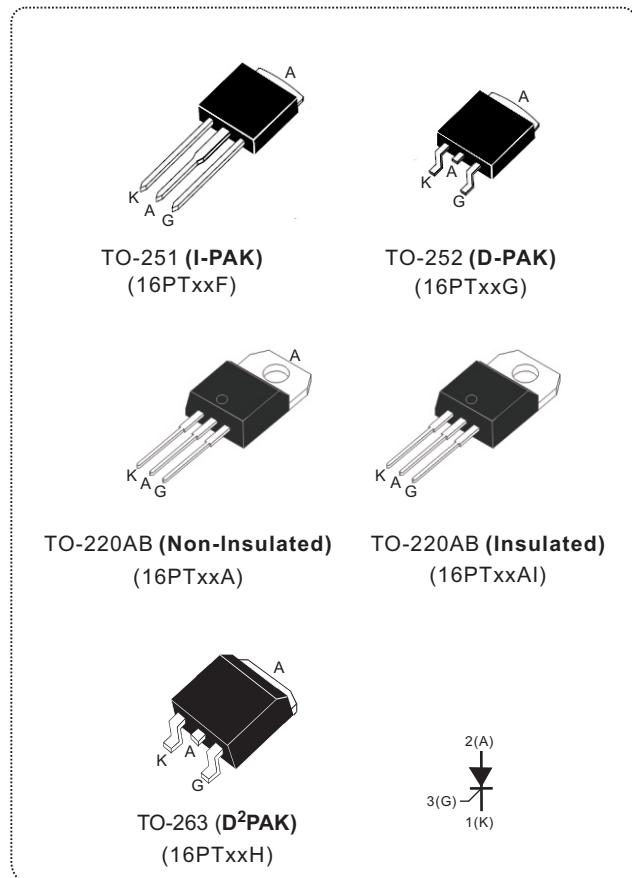
### Main Features

Symbol	Value	Unit
$I_{T(RMS)}$	16	A
$V_{DRM}/V_{RRM}$	600 to 1000	V
$I_{GT}$	25	mA

### DESCRIPTION

The 16PT series of silicon controlled rectifiers are high performance glass passivated technology, and are suitable for general purpose applications.

Using clip assembly technology, they provide a superior performance in surge current capabilities.



### ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS		VALUE	UNIT
RMS on-state current full sine wave (180° conduction angle )	$I_{T(RMS)}$	TO-251/TO-252 TO-220AB/TO-263	$T_c=110^\circ C$	16	A
		TO-220AB insulated	$T_c=86^\circ C$		
Average on-state current (180° conduction angle)	$I_{T(AV)}$	TO-251/TO-252 TO-220AB/TO-263	$T_c=110^\circ C$	10	A
		TO-220AB insulated	$T_c=86^\circ C$		
Non repetitive surge peak on-state current (full cycle, $T_j$ initial = 25°C)	$I_{TSM}$	$F=50$ Hz	$t = 20$ ms	190	A
		$F=60$ Hz	$t = 16.7$ ms	200	
$I^2t$ Value for fusing	$I^2t$	$t_p = 10$ ms		180	$A^2s$
Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$ , $t_r \leq 100$ ns	$dI/dt$	$F = 60$ Hz	$T_j = 125^\circ C$	50	$A/\mu s$
Peak gate current	$I_{GM}$	$T_p = 20$ $\mu s$	$T_j = 125^\circ C$	4	A
Maximum gate power	$P_{GM}$	$T_p = 20\mu s$	$T_j = 125^\circ C$	10	W
Average gate power dissipation	$P_{G(AV)}$	$T_j = 125^\circ C$		1	W
Repetitive peak off-state voltage	$V_{DRM}$	$T_j = 125^\circ C$		600 to 1000	V
Repetitive peak reverse voltage	$V_{RRM}$				
Storage temperature range	$T_{stg}$			- 40 to + 150	$^\circ C$
Operating junction temperature range	$T_j$			- 40 to + 125	

ELECTRICAL SPECIFICATIONS (T <sub>J</sub> = 25 °C unless otherwise specified)								
SYMBOL	TEST CONDITIONS			16PTxxxx		Unit		
				D	-			
I <sub>GT</sub>	V <sub>D</sub> = 12V, R <sub>L</sub> = 33Ω			Min.	4	2		
				Max.	10	25		
V <sub>GT</sub>				Max.	1.3	1.3		
V <sub>GD</sub>	V <sub>D</sub> = V <sub>DRM</sub> , R <sub>L</sub> = 3.3KΩ R <sub>GK</sub> = 220Ω	T <sub>j</sub> = 125°C		Min.	0.2	0.2		
I <sub>H</sub>	I <sub>T</sub> = 500mA, Gate open			Max.	10	40		
I <sub>L</sub>	I <sub>G</sub> = 1.2×I <sub>GT</sub>			Max.	20	60		
dV/dt	V <sub>D</sub> = 67% V <sub>DRM</sub> , Gate open		T <sub>j</sub> = 125°C	Min.	100	500		
V <sub>TM</sub>	I <sub>T</sub> = 32A, t <sub>P</sub> = 380μs		T <sub>j</sub> = 25°C	Max.	1.6			
I <sub>DRM</sub> I <sub>RRM</sub>	V <sub>D</sub> =V <sub>DRM</sub> , V <sub>R</sub> =V <sub>RRM</sub>		T <sub>j</sub> = 25°C	Max.	5			
	R <sub>GK</sub> = 220Ω		T <sub>j</sub> = 125°C	Max.	2			
V <sub>to</sub>	Threshold Voltage		T <sub>j</sub> = 125°C	Max.	0.77			
R <sub>d</sub>	Dynamic Resistance		T <sub>j</sub> = 125°C	Max.	23			

DYNAMIC CHARACTERISTICS						
SYMBOL	PARAMETER	TEST CONDITIONS		VALUE		UNIT
				Min.	Typ.	
t <sub>gt</sub>	Gate-controlled turn-on time	I <sub>TM</sub> = 40A, V <sub>D</sub> = V <sub>DRM</sub> (Max.), I <sub>G</sub> = 0.1A, dI <sub>G</sub> /dt = 5A/μs, T <sub>J</sub> = 25°C		-	2.0	-
t <sub>q</sub>	Commutated turn-off time	V <sub>D</sub> = 67% V <sub>DRM</sub> , I <sub>TM</sub> = 30A, V <sub>R</sub> = 25V, R <sub>GK</sub> = 100Ω, dI <sub>TM</sub> /dt = 30A/μs, dV <sub>D</sub> /dt = 50V/μs, T <sub>J</sub> = 125°C		-	70	-

THERMAL RESISTANCE							
SYMBOL	Parameter				VALUE	UNIT	
R <sub>th(j-c)</sub>	Junction to case (DC)		IPAK/DPAK/TO-220AB/TO-263		1.1	°C/W	
R <sub>th(j-a)</sub>	Junction to ambient	S = 1 cm <sup>2</sup>	TO-263(D <sup>2</sup> PAK)		45	°C/W	
		S = 0.5 cm <sup>2</sup>	TO-252(D-PAK)		70		
		TO-220AB		60			
		TO-251(I-PAK)		100			

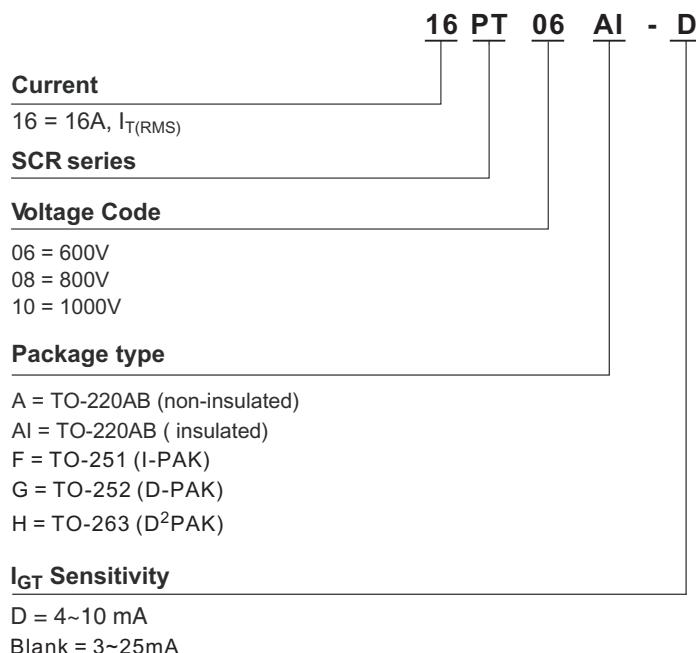
S=Copper surface under tab

PRODUCT SELECTOR						
PART NUMBER	VOLTAGE (xx)			SENSITIVITY	PACKAGE	
	600 V	800 V	1000 V			
16PTxxA/16PTxxAI	V	V	V	25 mA	TO-220AB	
16PTxxF	V	V	V	25 mA	I-PAK	
16PTxxG	V	V	V	25 mA	D-PAK	
16PTxxH	V	V	V	25 mA	D <sup>2</sup> PAK	
16PTxxA-D/16PTxxAI-D	V	V	V	4-10 mA	TO-220AB	
16PTxxF-D	V	V	V	4-10 mA	I-PAK	
16PTxxG-D	V	V	V	4-10 mA	D-PAK	
16PTxxH-D	V	V	V	4-10 mA	D <sup>2</sup> PAK	

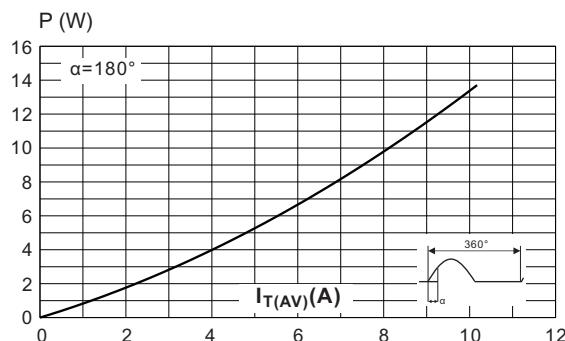
**ORDERING INFORMATION**

ORDERING TYPE	MARKING	PACKAGE	WEIGHT	BASE Q'TY	DELIVERY MODE
16PTxxA/16PTxxA-D	16PTxxA/16PTxxA-D	TO-220AB	2.0g	50	Tube
16PTxxAI/16PTxxAI-D	16PTxxAI/16PTxxAI-D	TO-220AB (insulated)	2.3g	50	Tube
16PTxxF/16PTxxF-D	16PTxxF/16PTxxF-D	TO-251(I-PAK)	0.40g	80	Tube
16PTxxG/16PTxxG-D	16PTxxG/16PTxxG-D	TO-252(D-PAK)	0.38g	80	Tube
16PTxxH/16PTxxH-D	16PTxxH/16PTxxH-D	TO-263(D <sup>2</sup> PAK)	2.0g	50	Tube

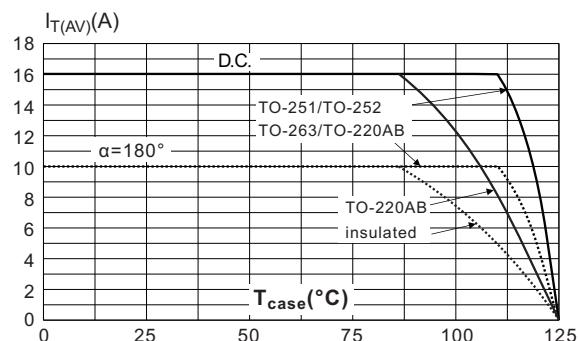
Note: xx = voltage

**ORDERING INFORMATION SCHEME**


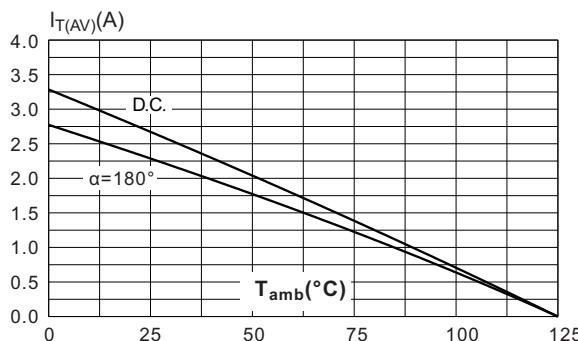
**Fig.1 Maximum average power dissipation versus average on-state current.**



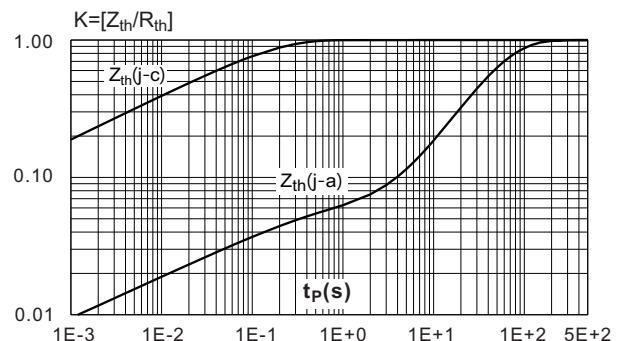
**Fig.2 Average and D.C. on-state current versus case temperature.**



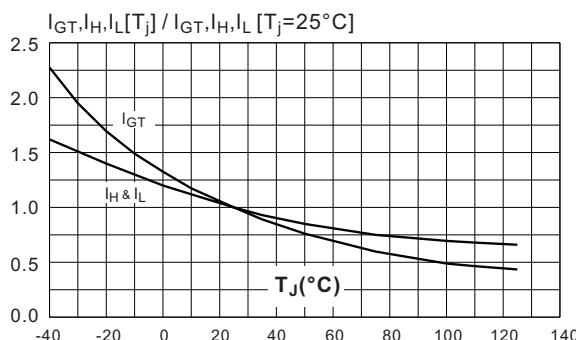
**Fig.3 Average and D.C. on-state current versus ambient temperature.  
(copper surface under tab:  $S=1\text{cm}^2$ )  
(D<sup>2</sup>PAK)**



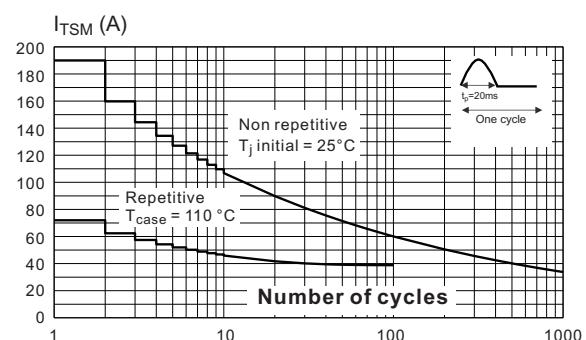
**Fig.4 Relative variation of thermal impedance versus pulse duration.**



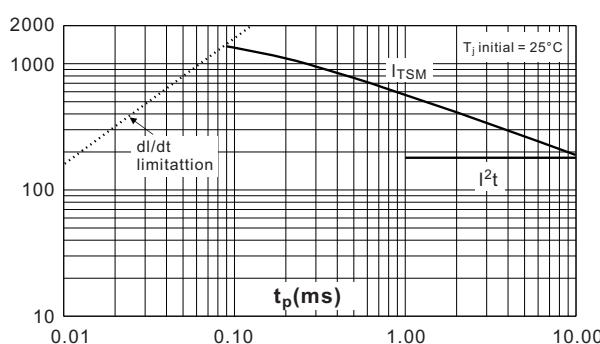
**Fig.5 Relative variation of gate trigger current, holding current and latching current and latching current versus junction temperature.**



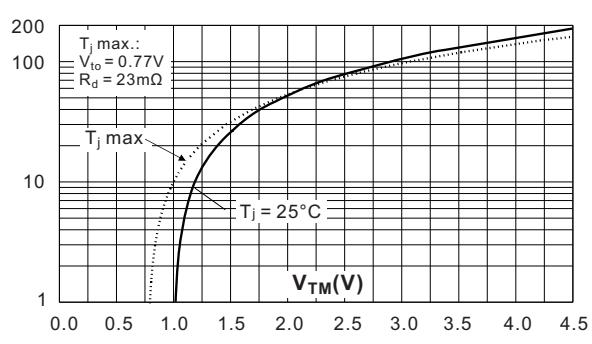
**Fig.6 Surge peak on-state current versus number of cycles.**



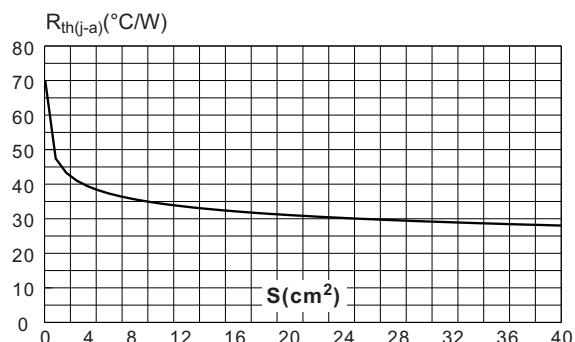
**Fig.7 Non-repetitive surge peak on-state current for a sinusoidal pulse with width t<sub>p</sub> < 10 ms, and corresponding values of I<sup>2</sup>t**



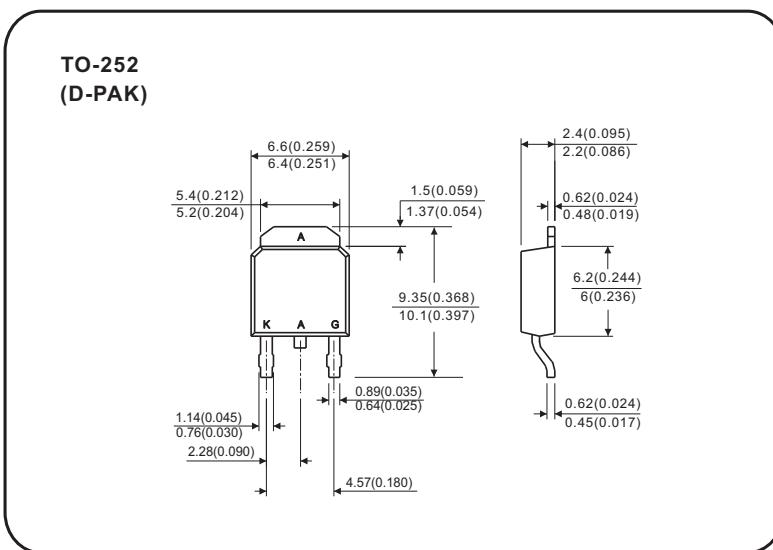
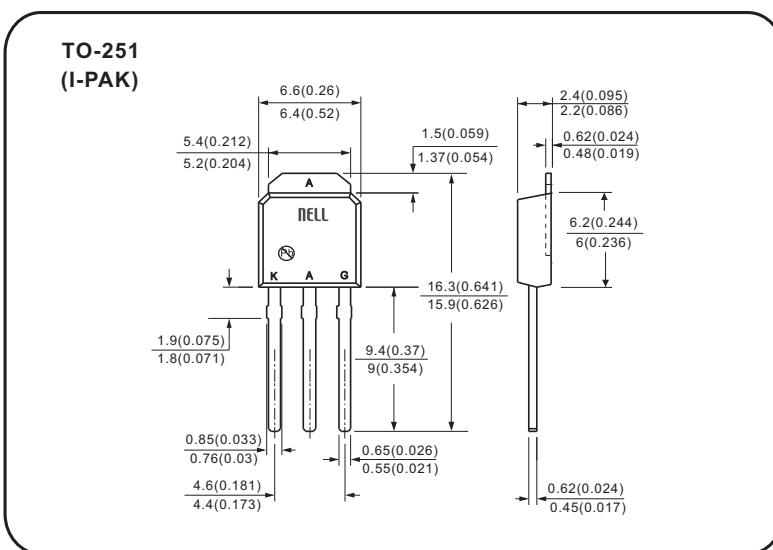
**Fig.8 On-state characteristics (maximum values)**



**Fig.9 Thermal resistance junction to ambient versus copper surface under tab (epoxy printed circuit board Fr4, copper thickness:35 µm)(D<sup>2</sup>PAK)**

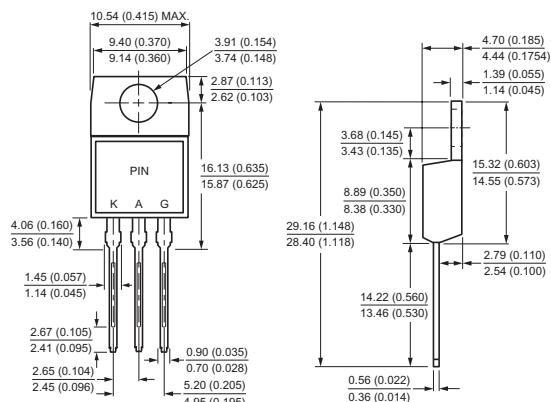
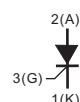
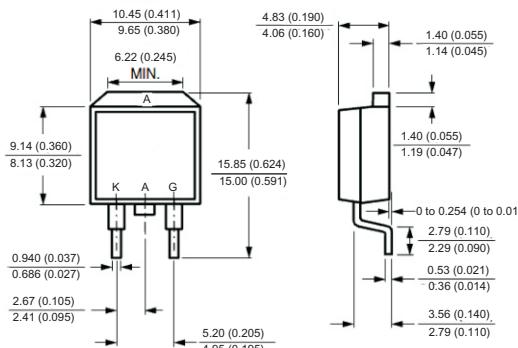


## Case Style



All dimensions in millimeters(inches)

## Case Style

**TO-220AB**

**TO-263(D<sup>2</sup>PAK)**


All dimensions in millimeters(inches)